

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s) : GOEBEL et al.
Serial No. : To Be Assigned
Filed : Herewith
For : SEMICONDUCTOR ARRANGEMENT AND
METHOD OF MANUFACTURE
Examiner : To Be Assigned
Group Art Unit : To Be Assigned

Assistant Commissioner
for Patents
Washington, D.C. 20231

PRELIMINARY AMENDMENT

SIR:

Please amend the above-identified application before examination as follows:

IN THE SPECIFICATION AND ABSTRACT:

In accordance with 37 C.F.R. § 1.121(b)(3), a Substitute Specification (including the Abstract but without claims) accompanies this response. It is respectfully requested that the Substitute Specification be entered to replace the Specification of record.

IN THE CLAIMS:

Without prejudice, please cancel original claims 1-7 and cancel substitute claims 1-3. Please add new claims 8-13 as shown below:

--8. (New) A semiconductor chip comprising:

A¹ a first layer of a first conductivity type having at least two partial layers, a first